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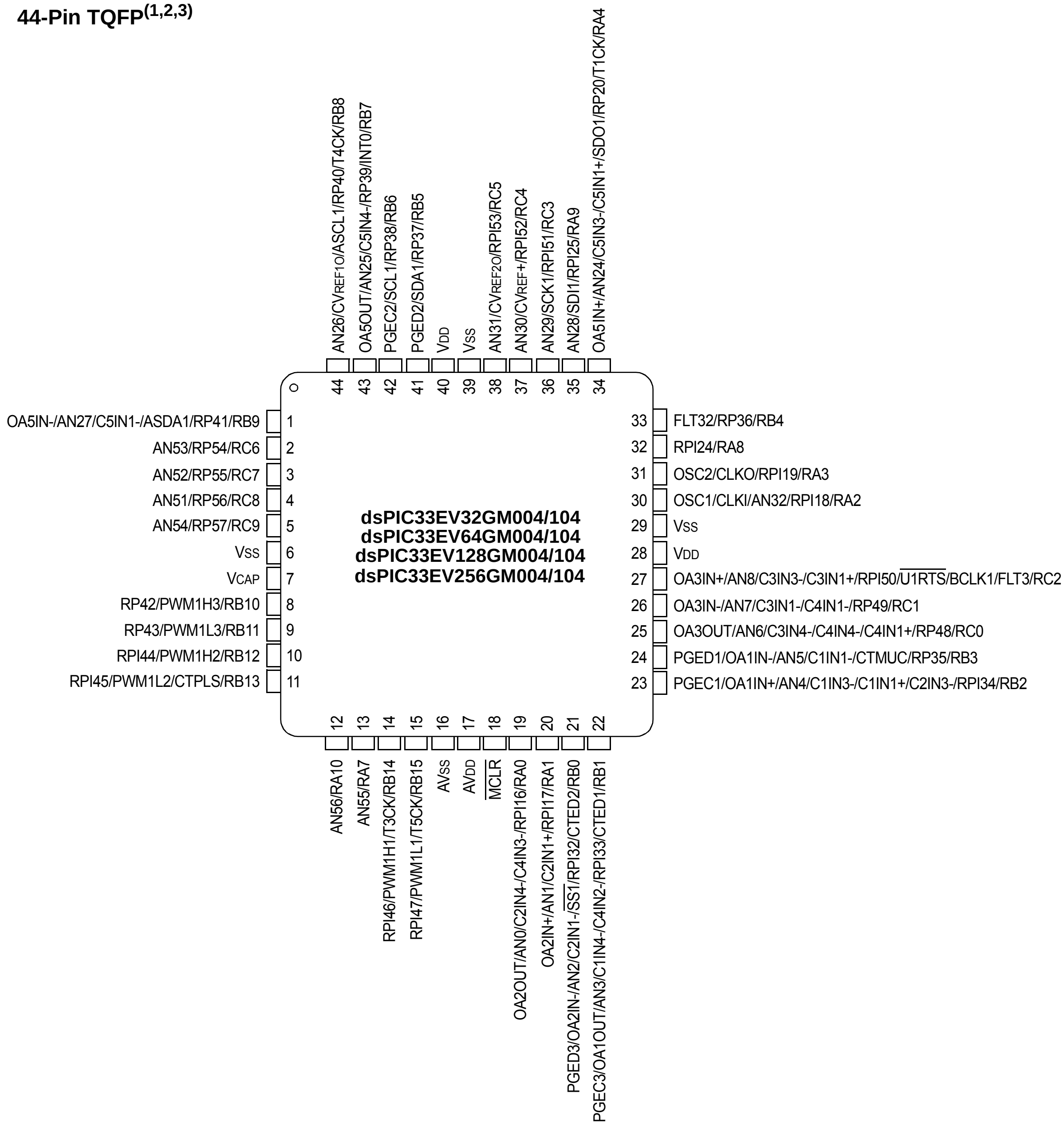
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev32gm002-e-ss

Pin Diagrams (Continued)

44-Pin TQFP(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 “Peripheral Pin Select (PPS)”** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

4.2.5 X AND Y DATA SPACES

The dsPIC33EVXXXGM00X/10X family core has two Data Spaces: X and Y. These Data Spaces can be considered either separate (for some DSP instructions) or as one unified, linear address range (for MCU instructions). The Data Spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X DS is used by all instructions and supports all addressing modes. The X DS has separate read and write data buses. The X read data bus is the read data path for all instructions that view the DS as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (MAC class).

The Y DS is used in concert with the X DS by the MAC class of instructions (CLR, ED, EDAC, MAC, MOVSAC, MPY, MPY.N and MSC) to provide two concurrent data read paths.

Both the X and Y Data Spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to the X Data Space.

All data memory writes, including in DSP instructions, view Data Space as combined X and Y address space. The boundary between the X and Y Data Spaces is device-dependent and is not user-programmable.

TABLE 4-7: ADC1 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC1 Data Buffer 0																xxxx
ADC1BUF1	0302	ADC1 Data Buffer 1																xxxx
ADC1BUF2	0304	ADC1 Data Buffer 2																xxxx
ADC1BUF3	0306	ADC1 Data Buffer 3																xxxx
ADC1BUF4	0308	ADC1 Data Buffer 4																xxxx
ADC1BUF5	030A	ADC1 Data Buffer 5																xxxx
ADC1BUF6	030C	ADC1 Data Buffer 6																xxxx
ADC1BUF7	030E	ADC1 Data Buffer 7																xxxx
ADC1BUF8	0310	ADC1 Data Buffer 8																xxxx
ADC1BUF9	0312	ADC1 Data Buffer 9																xxxx
ADC1BUFA	0314	ADC1 Data Buffer 10																xxxx
ADC1BUFB	0316	ADC1 Data Buffer 11																xxxx
ADC1BUFC	0318	ADC1 Data Buffer 12																xxxx
ADC1BUFD	031A	ADC1 Data Buffer 13																xxxx
ADC1BUFE	031C	ADC1 Data Buffer 14																xxxx
ADC1BUFF	031E	ADC1 Data Buffer 15																xxxx
AD1CON1	0320	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM1	FORM0	SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG2	VCFG1	VCFG0	—	—	CSCNA	CHPS1	CHPS0	BUFS	SMPI4	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0	ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
AD1CHS123	0326	—	—	—	CH123SB2	CH123SB1	CH123NB1	CH123NB0	CH123SB0	—	—	—	CH123SA2	CH123SA1	CH123NA1	CH123NA0	CH123SA0	0000
AD1CHS0	0328	CH0NB	—	CH0SB5	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	CH0NA	—	CH0SA5	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	0000
AD1CSSH	032E	CSS<31:24>								—	—	—	—	CSS<19:16>				0000
AD1CSSL	0330	CSS<15:0>																0000
AD1CON4	0332	—	—	—	—	—	—	—	ADDMAEN	—	—	—	—	—	DMABL2	DMABL1	DMABL0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-8: CTMU REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CTMUCON1	033A	CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	—	—	—	—	—	—	—	—	0000
CTMUCON2	033C	EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—	0000
CTMUICON	033E	ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-22: PMD REGISTER MAP FOR dsPIC33EVXXXGM00X/10X FAMILY DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	—	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD(1)	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	—	—	—	—	—	—	—	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—		—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	—	—	—	—	0000
PMD8	076E	—	—	—	SENT2MD	SENT1MD	—	—	DMTMD	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This feature is available only on dsPIC33EVXXXGM10X devices.

TABLE 4-41: PORTF REGISTER MAP FOR dsPIC33EVXXXGMX06 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E64	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TRISF<1:0>		0003
PORTF	0E66	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RF<1:0>		xxxx
LATF	0E68	—	—	—	—	—	—	—	—	—	—	—	—	—	—	LATF<1:0>		xxxx
ODCF	0E6A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ODCF<1:0>		0000
CNENF	0E6C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNIEF<1:0>		0000
CNPUF	0E6E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPUF<1:0>		0000
CNPDF	0E70	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPDF<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-42: PORTG REGISTER MAP FOR dsPIC33EVXXXGMX06 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISG	0E78	—	—	—	—	—	—	TRISG<9:6>				—	—	—	—	—	—	03C0
PORTG	0E7A	—	—	—	—	—	—	RG<9:6>				—	—	—	—	—	—	xxxx
LATG	0E7C	—	—	—	—	—	—	LATG<9:6>				—	—	—	—	—	—	xxxx
ODCG	0E7E	—	—	—	—	—	—	ODCG<9:6>				—	—	—	—	—	—	0000
CNENG	0E80	—	—	—	—	—	—	CNIEG<9:6>				—	—	—	—	—	—	0000
CNPUG	0E82	—	—	—	—	—	—	CNPUG<9:6>				—	—	—	—	—	—	0000
CNPDG	0E84	—	—	—	—	—	—	CNPDG<9:6>				—	—	—	—	—	—	0000
ANSELG	0E86	—	—	—	—	—	—	ANSG<9:6>				—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-45: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.4.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

> **Note:** For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

> **Note:** Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.4.4 MAC INSTRUCTIONS

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set, {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must, therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

> **Note:** Register Indirect with Register Offset Addressing mode is available only for W9 (in X Data Space) and W11 (in Y Data Space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.4.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (Branch) instructions use 16-bit signed literals to specify the Branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ULNK, the source of an operand or result is implied by the opcode itself. Certain operations, such as a NOP, do not have any operands.

4.7.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The `TBLRDL` and `TBLWTL` instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through the Data Space. The `TBLRDH` and `TBLWTH` instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. The `TBLRDL` and `TBLWTL` instructions access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

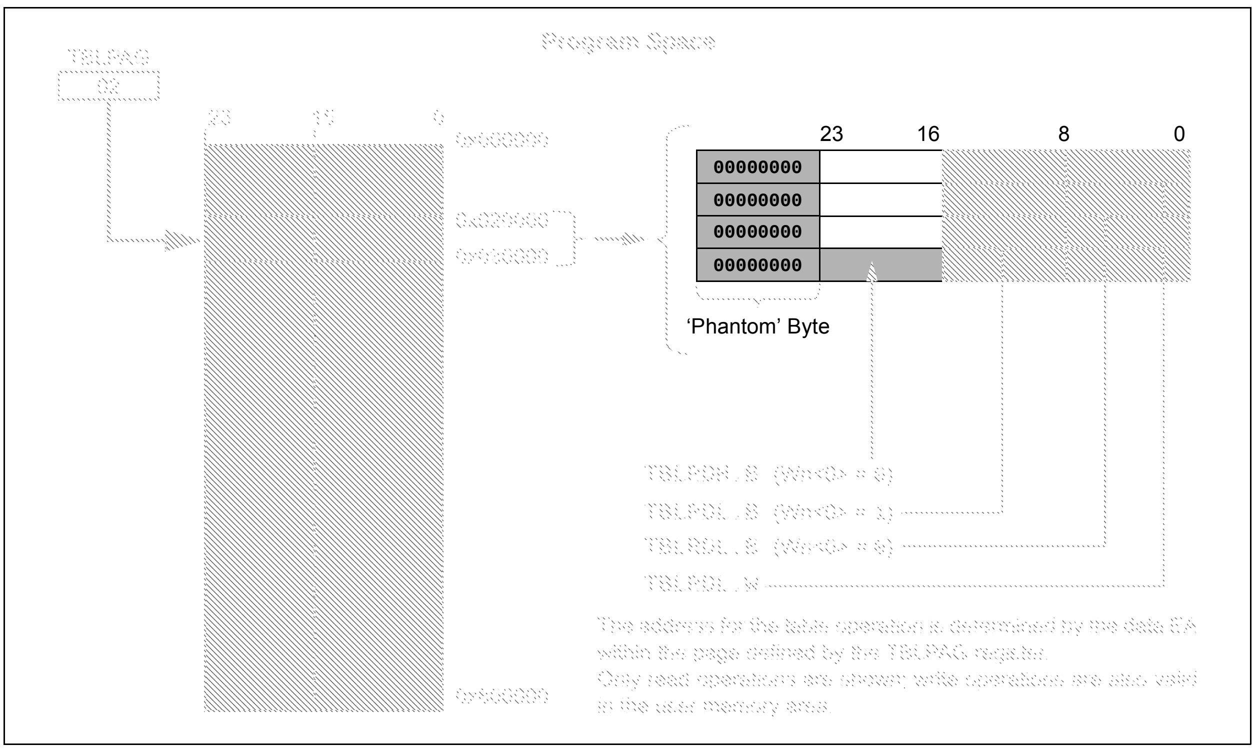
Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- `TBLRDL` (Table Read Low):
  - In Word mode, this instruction maps the lower word of the Program Space location (P<15:0>) to a data address (D<15:0>).
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.
- `TBLRDH` (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. The 'phantom' byte (D<15:8>) is always '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, as in the `TBLRDL` instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

Similarly, two table instructions, `TBLWTH` and `TBLWTL`, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space. Accessing the program memory with table instructions is shown in Figure 4-18.

FIGURE 4-18: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



REGISTER 7-6: INTCON4: INTERRUPT CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R-0, HS, SC	R-0, HS, SC
—	—	—	—	—	—	ECCDBE(1)	SGHT
bit 7							bit 0

Legend:	HS = Hardware Settable bit	SC = Software Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as ‘0’

bit 1 **ECCDBE:** ECC Double-Bit Error Trap bit(1)
1 = ECC double-bit error trap has occurred
0 = ECC double-bit error trap has not occurred

bit 0 **SGHT:** Software-Generated Hard Trap Status bit
1 = Software-generated hard trap has occurred
0 = Software-generated hard trap has not occurred

Note 1: ECC double-bit error causes a generic hard trap.

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this may not be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps, based on this device operating speed. If the device is placed in Doze mode, with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled, using the appropriate PMDx control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have any effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMDx register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMDx register by default.

> **Note:** If a PMDx bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMDx bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

REGISTER 19-2: I2CxCON2: I2Cx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6 **PCIE:** Stop Condition Interrupt Enable bit (I^2C Slave mode only).
1 = Enables interrupt on detection of Stop condition
0 = Stop detection interrupts are disabled

bit 5 **SCIE:** Start Condition Interrupt Enable bit (I^2C Slave mode only)
1 = Enables interrupt on detection of Start or Restart conditions
0 = Start detection interrupts are disabled

bit 4 **BOEN:** Buffer Overwrite Enable bit (I^2C Slave mode only)
1 = The I2CxRCV register bit is updated and an ACK is generated for a received address/data byte, ignoring the state of the I2COV bit only if the RBF bit = 0
0 = The I2CxRCV register bit is only updated when I2COV is clear

bit 3 **SDAHT:** SDAx Hold Time Selection bit
1 = Minimum of 300 ns hold time on SDAx after the falling edge of SCLx
0 = Minimum of 100 ns hold time on SDAx after the falling edge of SCLx

bit 2 **SBCDE:** Slave Mode Bus Collision Detect Enable bit (I^2C Slave mode only)
If, on the rising edge of SCLx, SDAx is sampled low when the module is outputting a high state, the BCL bit is set and the bus goes Idle. This Detection mode is only valid during data and ACK transmit sequences.
1 = Slave bus collision interrupts are enabled
0 = Slave bus collision interrupts are disabled

bit 1 **AHEN:** Address Hold Enable bit (I^2C Slave mode only)
1 = Following the 8^{th} falling edge of SCLx for a matching received address byte; the SCLREL bit (I2CxCON1<12>) will be cleared and the SCLx will be held low
0 = Address holding is disabled

bit 0 **DHEN:** Data Hold Enable bit (I^2C Slave mode only)
1 = Following the 8^{th} falling edge of SCLx for a received data byte; slave hardware clears the SCLREL bit (I2CxCON1<12>) and the SCLx is held low
0 = Data holding is disabled

REGISTER 22-4: CxFCTRL: CANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FSA5	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

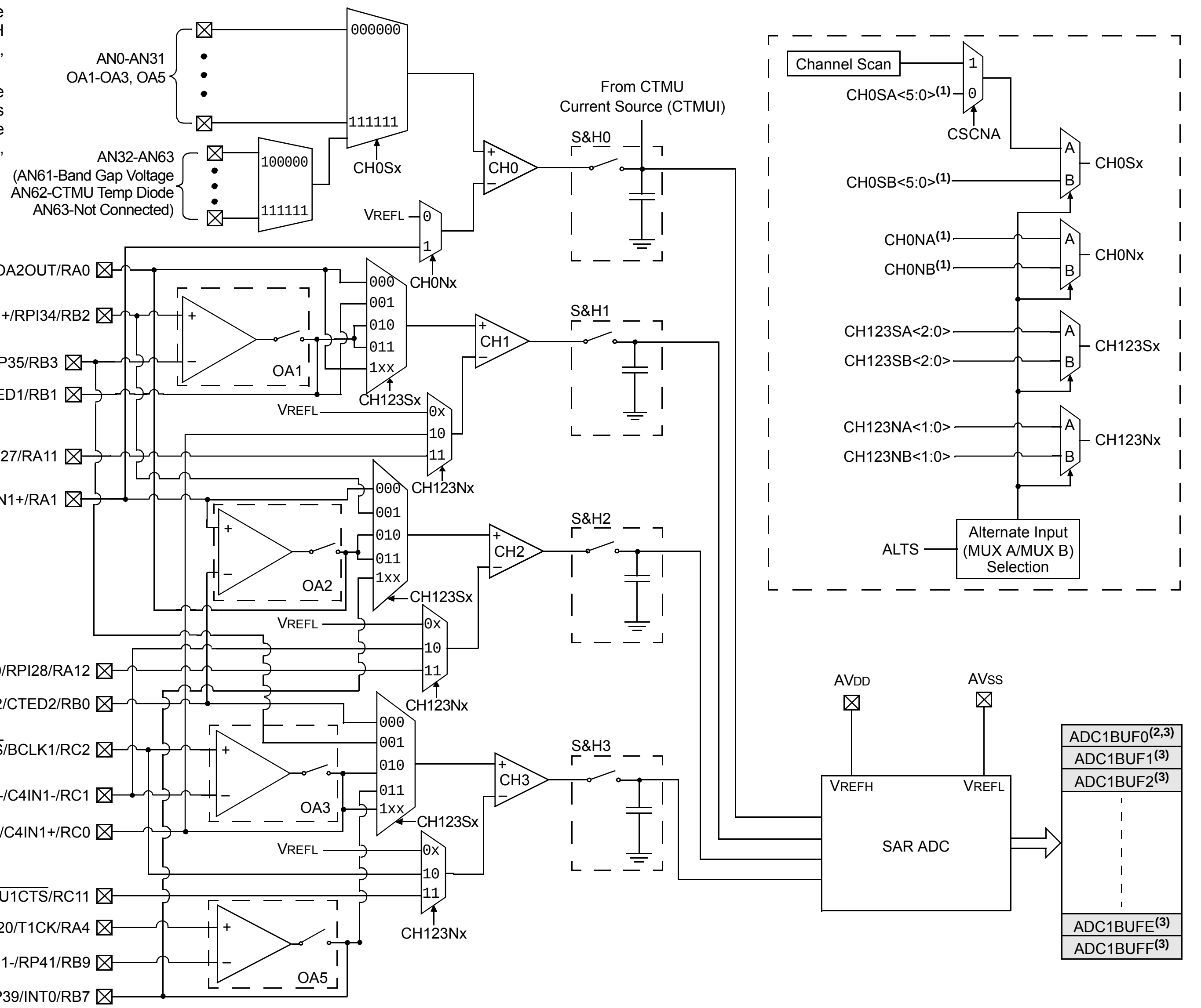
bit 12-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FSA<5:0>:** FIFO Area Starts with Buffer bits
11111 = Receive Buffer RB31
11110 = Receive Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

FIGURE 24-1: ADCx MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CH0Nx, CH123Sx and CH123Nx.



Note 1: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
2: When ADDMAEN (ADxCON4<8>) = 0, ADC1BUF0-ADC1BUFF are used.
3: When ADDMAEN (ADxCON4<8>) = 1 enabling DMA, only ADC1BUF0 is used.

TABLE 30-24: TIMER2 AND TIMER4 (TYPE B TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic[1]		Min.	Typ.	Max.	Units	Conditions
TB10	TTXH	TxCK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescaler Value (1, 8, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescaler Value (1, 8, 64, 256)
TB15	TTXP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
TB20	TCKEXT-MRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-25: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic[1]		Min.	Typ.	Max.	Units	Conditions
TC10	TTXH	TxCK High Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC11	TTXL	TxCK Low Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC15	TTXP	TxCK Input Period	Synchronous, with Prescaler	2 TCY + 40	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
TC20	TCKEXT-MRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-18: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

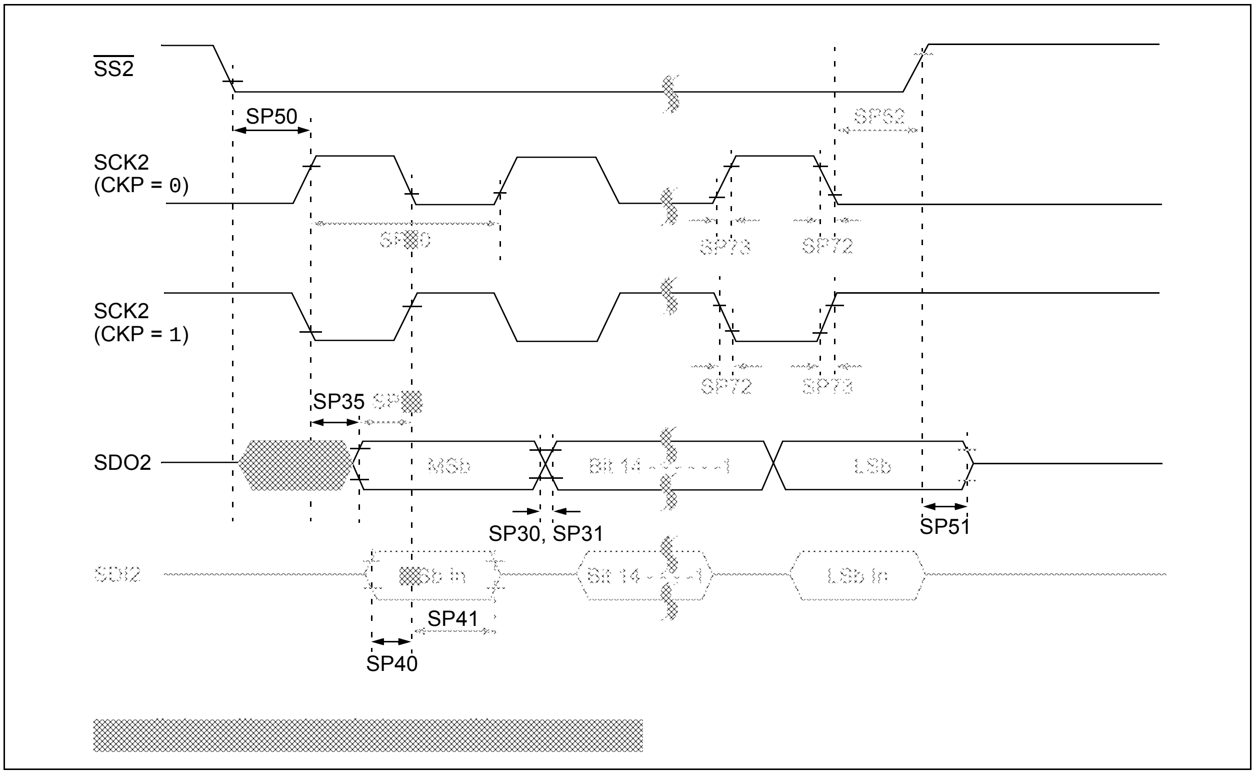
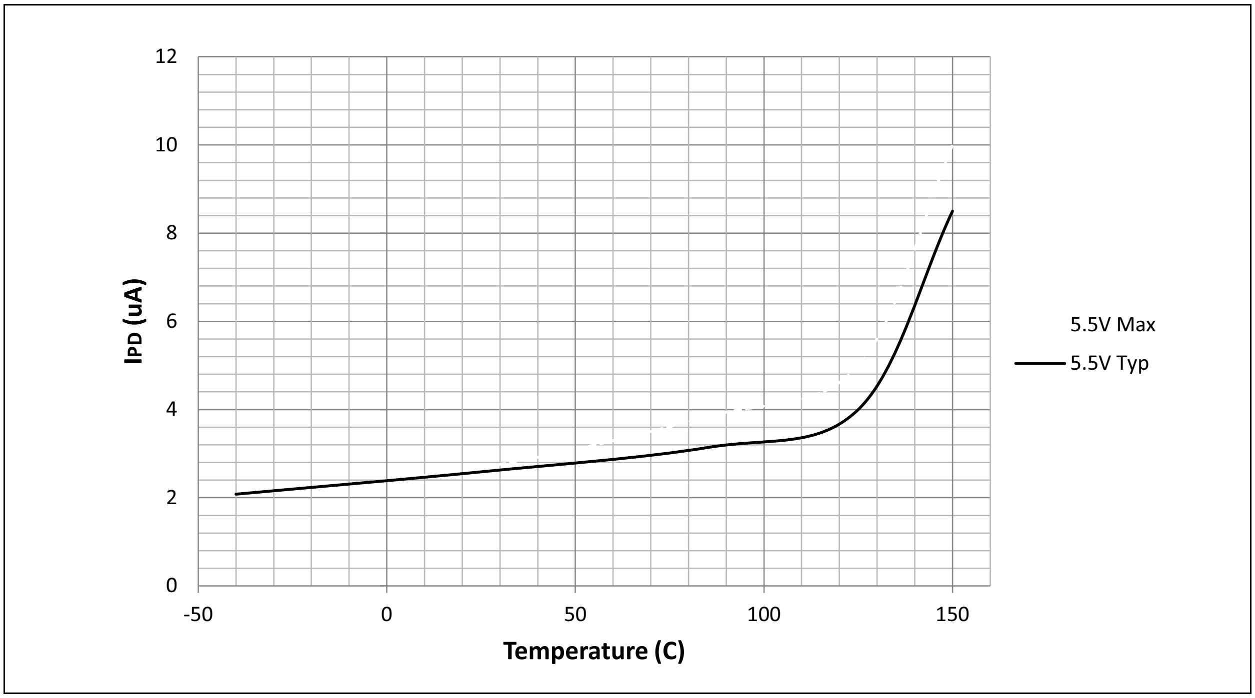
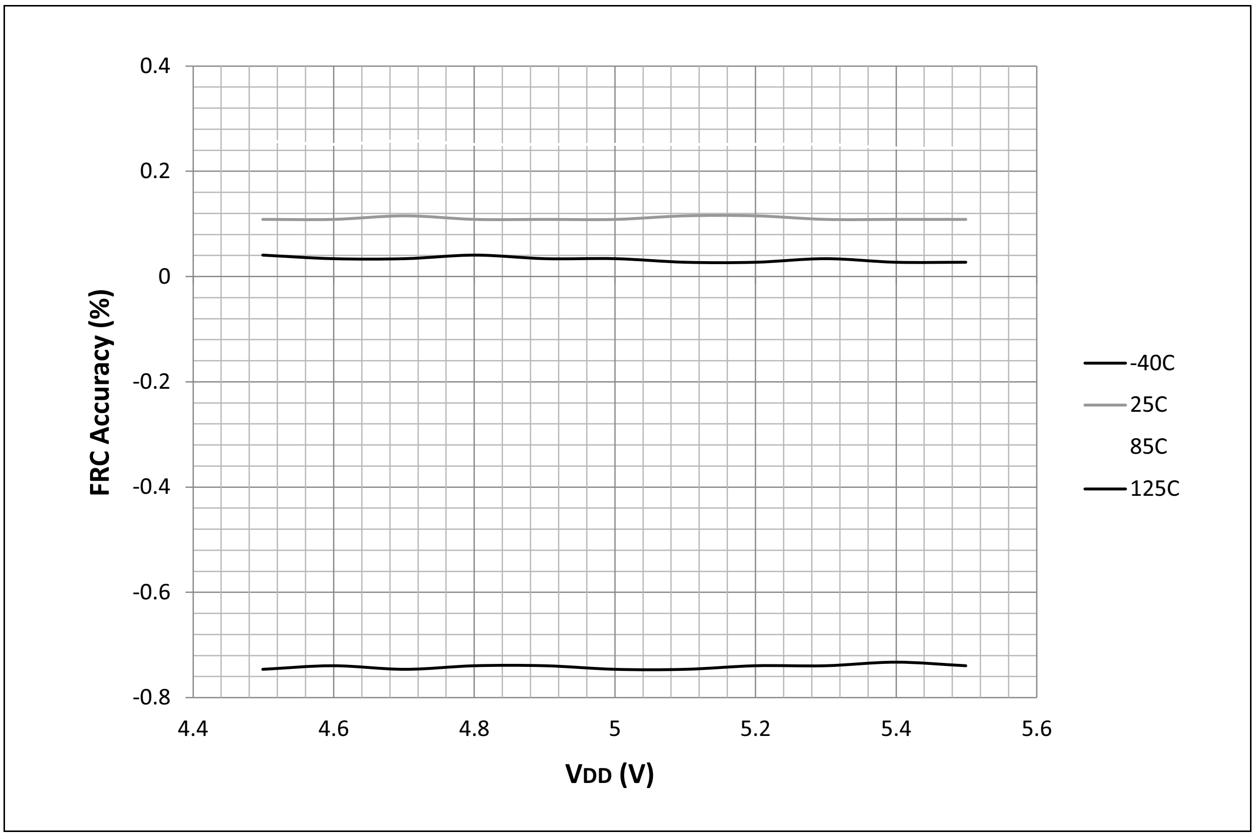


FIGURE 32-19: TYPICAL/MAXIMUM ΔIWDT vs. TEMPERATURE



32.5 FRC

FIGURE 32-20: TYPICAL FRC ACCURACY vs. VDD



32.18 ADC INL

FIGURE 32-45: TYPICAL INL (V_{DD} = 5.5V, -40°C)

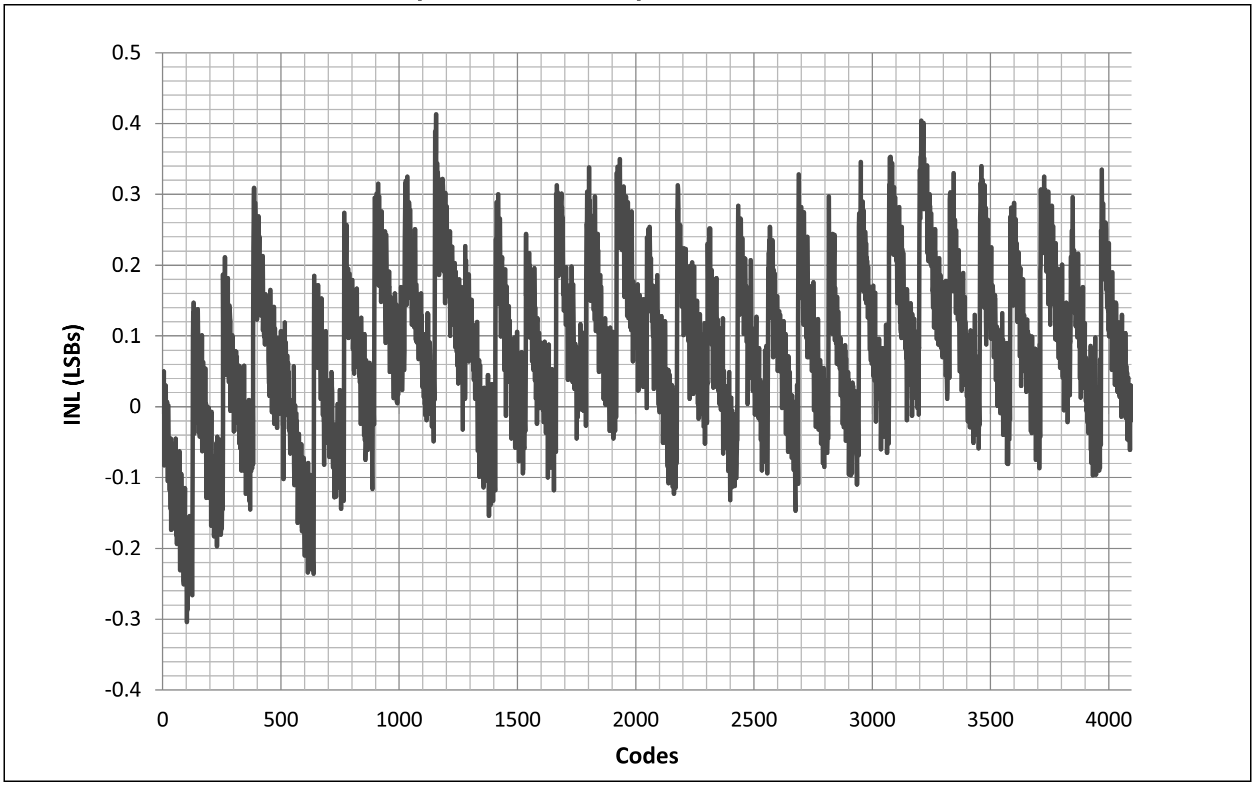


FIGURE 32-46: TYPICAL INL (V_{DD} = 5.5V, +25°C)

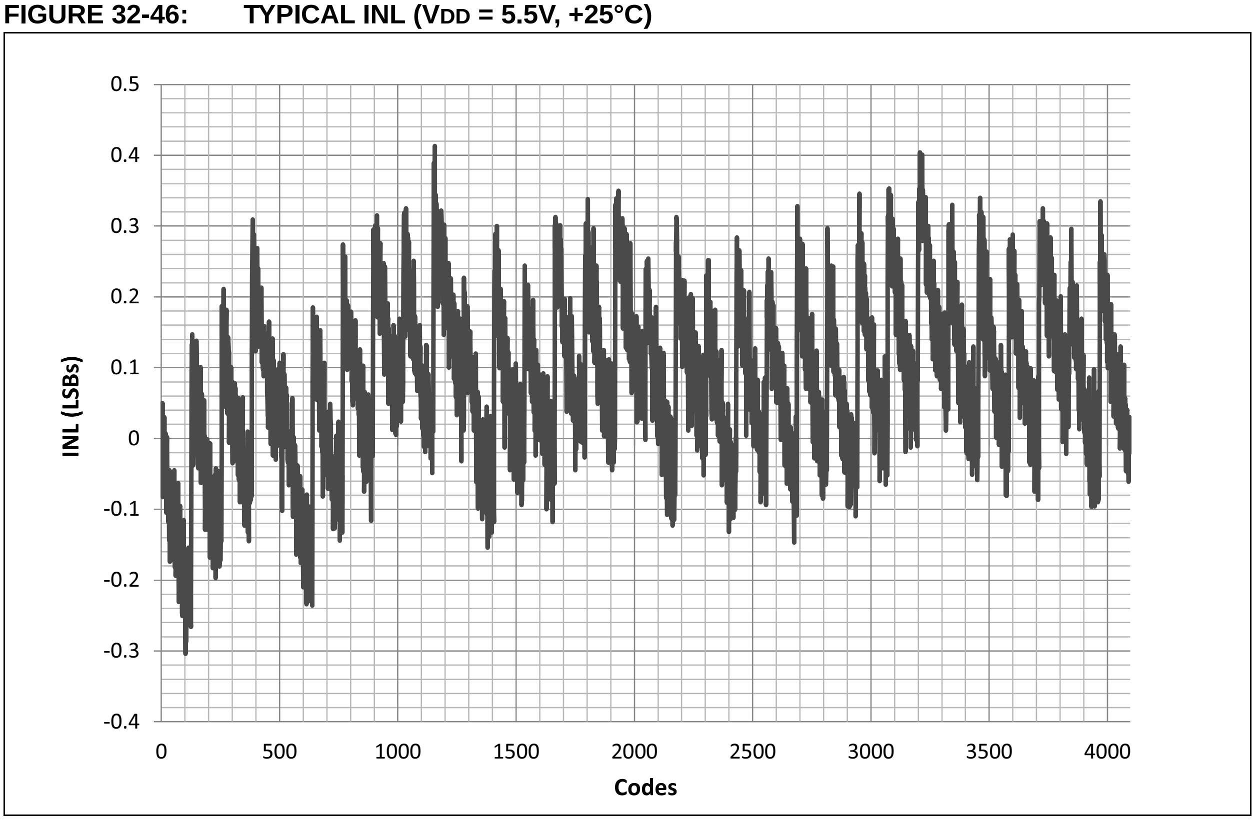


FIGURE 33-3: TYPICAL IDD vs. VDD (EC MODE, 20 MIPS)

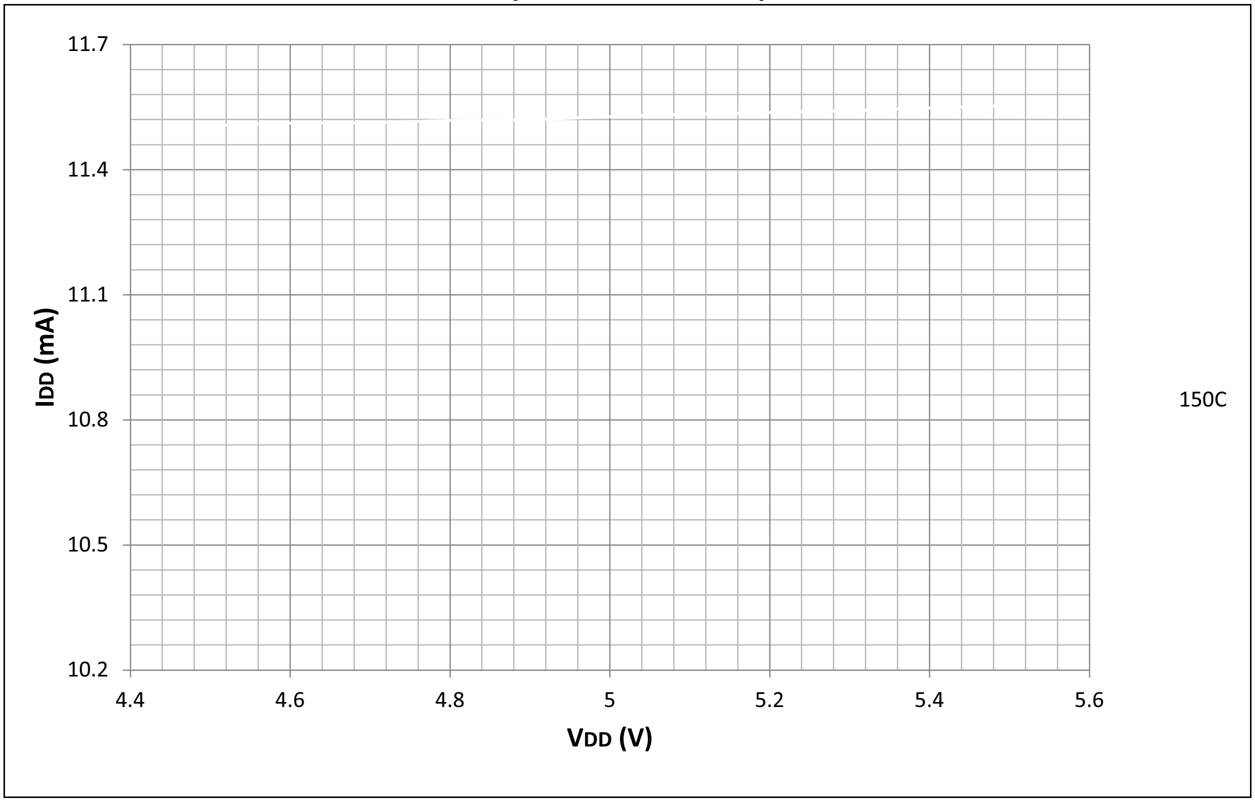
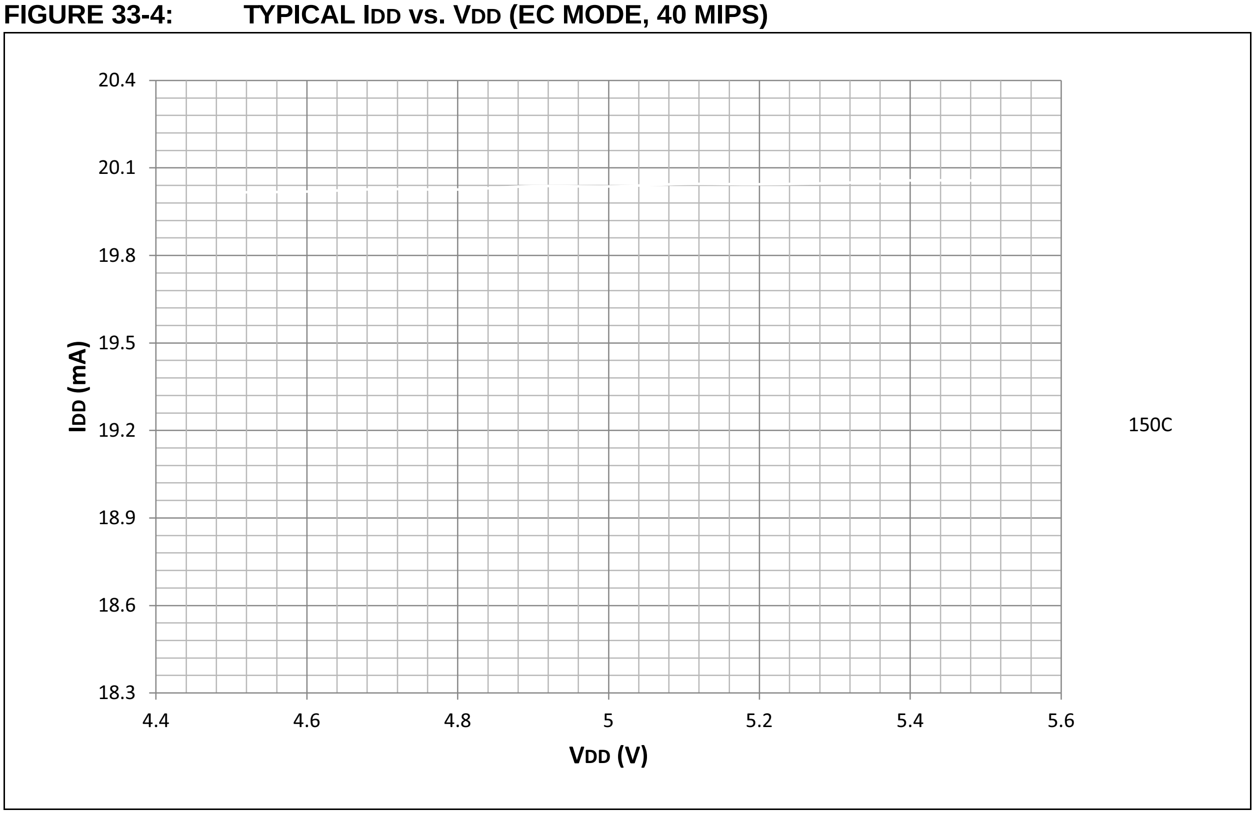


FIGURE 33-4: TYPICAL IDD vs. VDD (EC MODE, 40 MIPS)

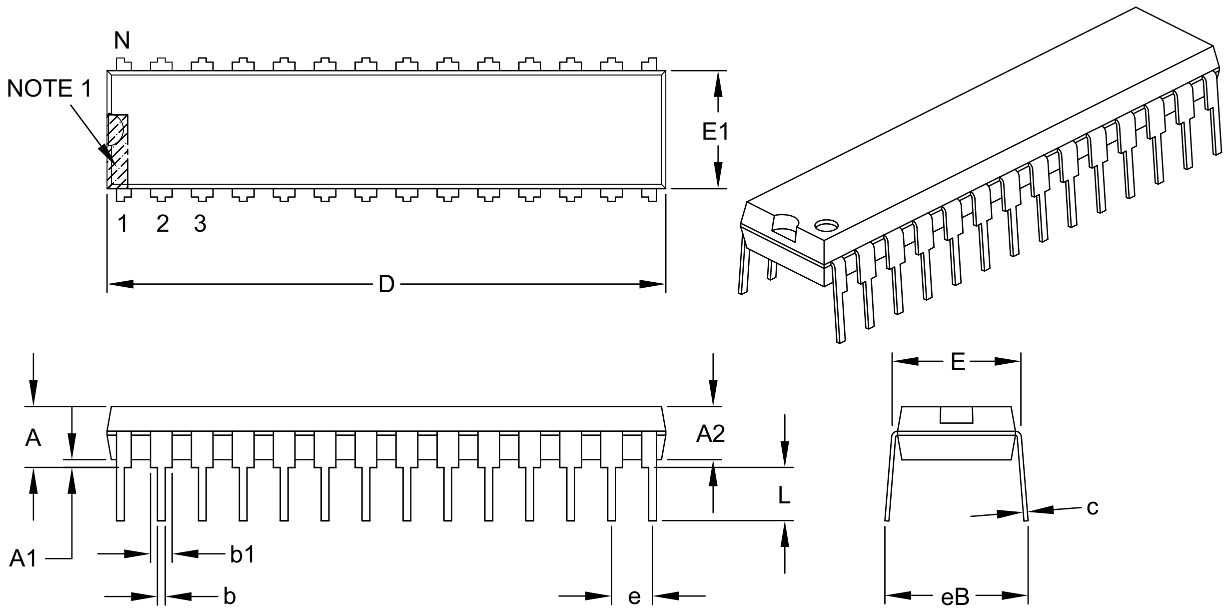


34.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	INCHES	
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

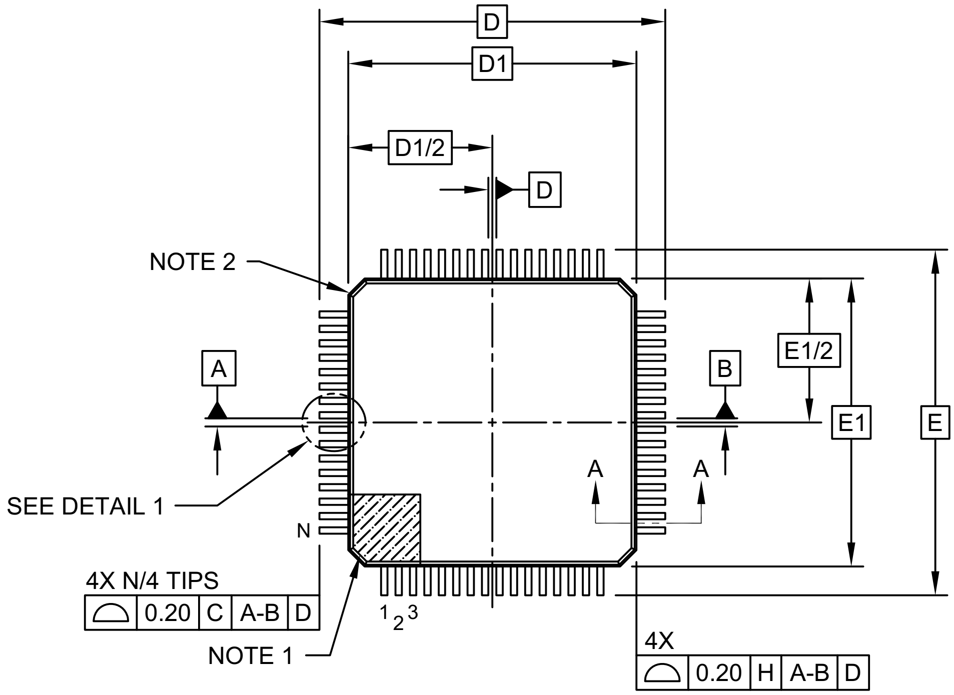
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

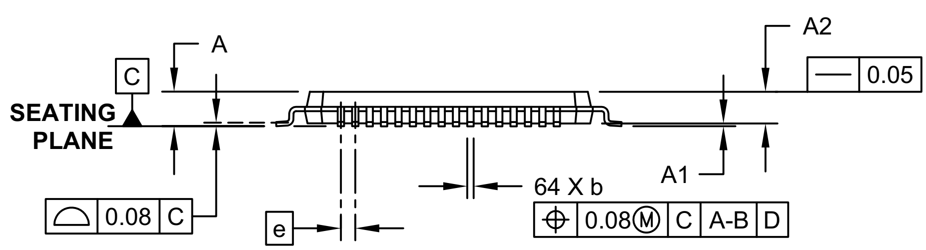
Microchip Technology Drawing C04-070B

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

Microchip Technology Drawing C04-085C Sheet 1 of 2